ABSTRACT OF THE DISCLOSURE

WAFER POLISHING APPARATUS WITH RETAINER RING

A rubber sheet is arranged between a head body and a retainer ring of a wafer holding head. Two O-rings air-tightly close a space between the periphery of the rubber sheet, which is located above the retainer ring, and the head body. When a pump supplies the compressed air to the space, the periphery of the rubber sheet is elastically deformed to press the retainer ring under uniform pressure.

(Fig. 2)